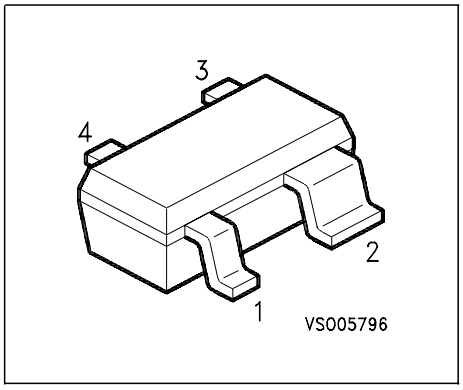
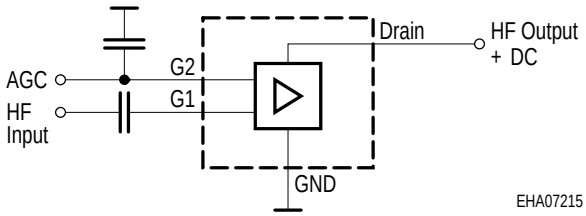
Dual - MOS FET Monolithic Integrated Circuit

- For low noise, high gain controlled input stages up to 1GHz
- Operating voltage 5V
- Integrated stabilized bias network





ESD: **E**lectro**s**tatic **d**ischarge sensitive device, observe handling precaution!

Class 2 (2000V - 4000V) pin to pin **H**uman **B**ody **M**odel

Type	Marking	Pin Configuration						Package
BF1005R	MZs	1=D	2=S	3=G1	4=G2	-	-	SOT143R

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	8	V
Continuous drain current	I_D	25	mA
Gate 1/ gate 2-source current	$\pm I_{G1/2SM}$	10	
Gate 1 (external biasing)	$+V_{G1SE}$	3	V
Total power dissipation, $T_S \leq 76°C$	P_{tot}	200	mW
Storage temperature	T_{stg}	-55 ... 150	°C
Channel temperature	T_{ch}	150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point[1)]	R_{thchs}	≤370	K/W

[1]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Note:
It is not recommended to apply external DC-voltage on Gate 1 in active mode.

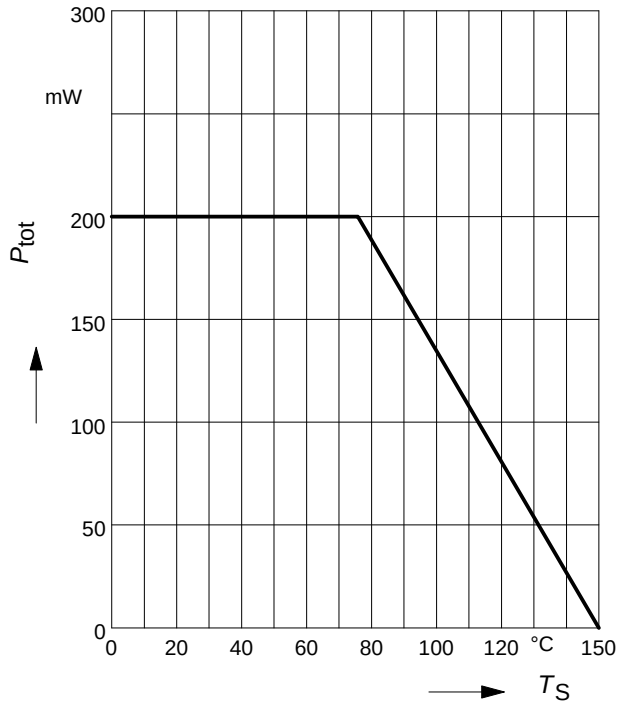
Electrical Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Drain-source breakdown voltage I_D = 650 µA, V_{G1S} = 0 V, V_{G2S} = 0 V	$V_{(BR)DS}$	12	-	-	V
Gate1-source breakdown voltage $+I_{G1S}$ = 10 mA, V_{G2S} = 0 V, V_{DS} = 0 V	$+V_{(BR)G1SS}$	8	-	12	
Gate2 source breakdown voltage $\pm I_{G2S}$ = 10 mA, V_{G1S} = 0 V, V_{DS} = 0 V	$\pm V_{(BR)G2SS}$	8	-	13	
Gate1-source leakage current V_{G1S} = 6 V, V_{G2S} = 0 V	$+I_{G1SS}$	-	100	-	µA
Gate 2 source leakage current $\pm V_{G2S}$ = 8 V, V_{G1S} = 0 V, V_{DS} = 0 V	$\pm I_{G2SS}$	-	-	50	nA
Drain current V_{DS} = 5 V, V_{G1S} = 0 , V_{G2S} = 4 V	I_{DSS}	-	-	800	µA
Operating current (selfbiased) V_{DS} = 5 V, V_{G2S} = 4 V	I_{DSO}	8	10	-	mA
Gate2-source pinch-off voltage V_{DS} = 5 V, I_D = 100 µA	$V_{G2S(p)}$	-	1	-	V

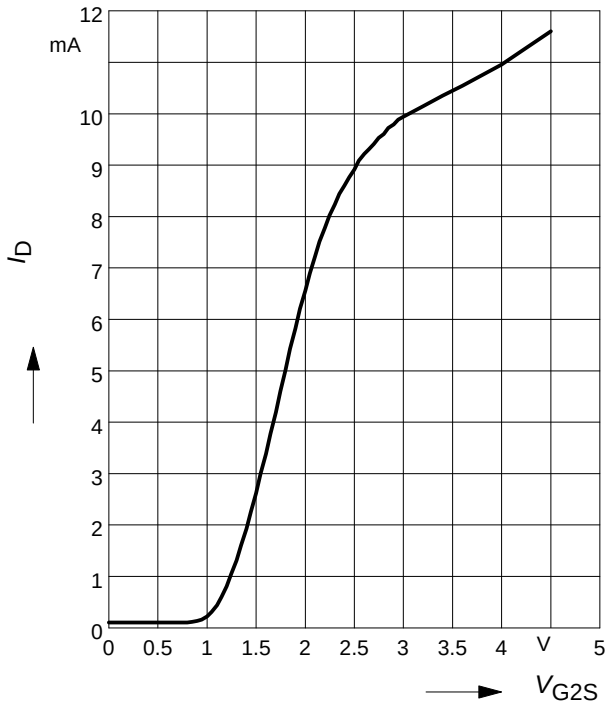
Electrical Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Forward transconductance V_{DS} = 5 V, V_{G2S} = 4 V	g_{fs}	-	24	-	mS
Gate1 input capacitance V_{DS} = 5 V, V_{G2S} = 4 V, f = 1 MHz	C_{g1ss}	-	2.1	2.5	pF
Output capacitance V_{DS} = 5 V, V_{G2S} = 4 V, f = 100 MHz	C_{dss}	-	1.3	-	
Power gain (self biased) V_{DS} = 5 V, V_{G2S} = 4 V, f = 800 MHz	G_{ps}	-	19	-	dB
Noise figure (self biased) V_{DS} = 5 V, V_{G2S} = 4 V, f = 800 MHz	F	-	1.4	-	dB
Gain control range V_{DS} = 5 V, V_{G2S} = 4...0 V, f = 800 MHz	ΔG_{ps}	40	50	-	

Total power dissipation $P_{tot} = f(T_S)$

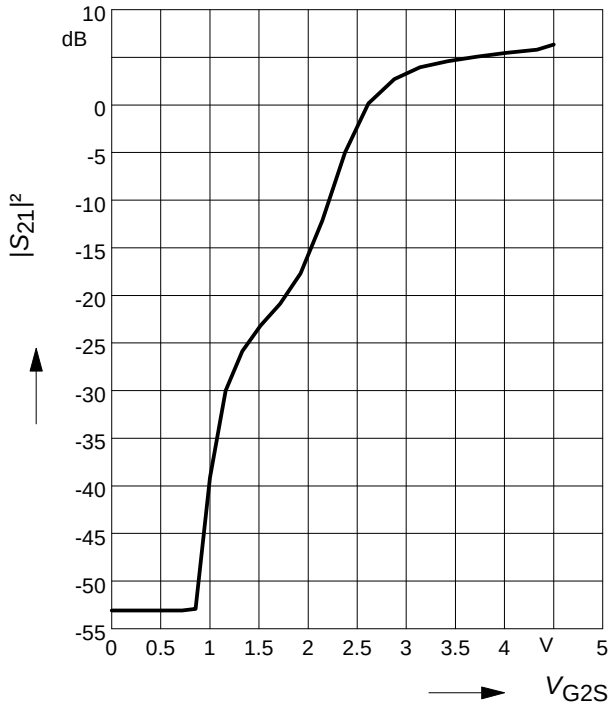


Drain current $I_D = f(V_{G2S})$



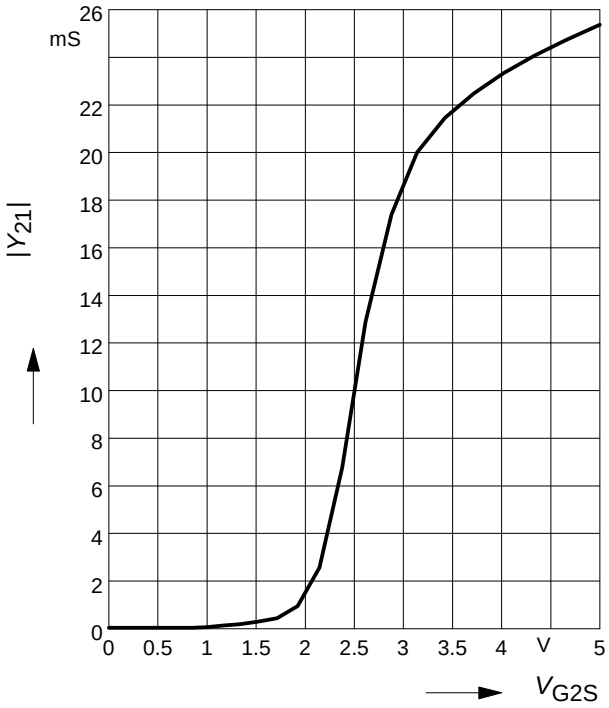
Insertion power gain

$|S_{21}|^2 = f(V_{G2S})$

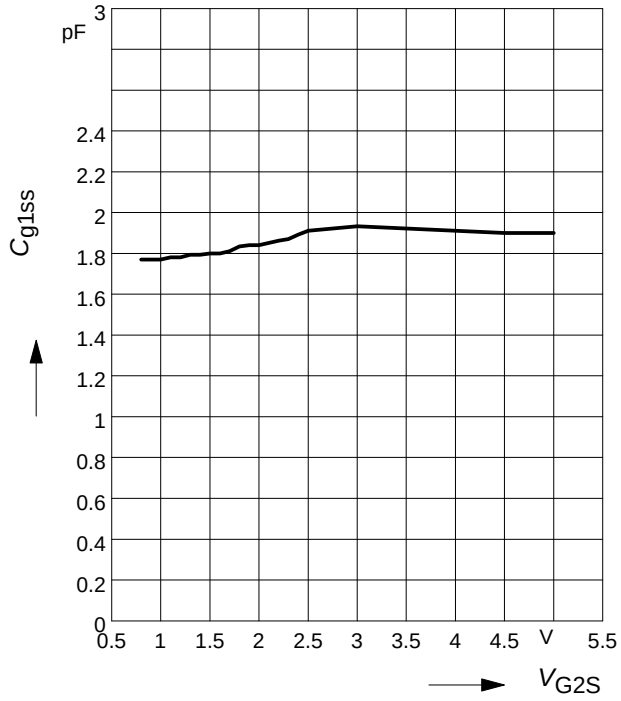


Forward transfer admittance

$|Y_{21}| = f(V_{G2S})$



Gate 1 input capacitance $C_{g1ss}= f(V_{g2s})$
f = 200MHz



Output capacitance $C_{dss} = f(V_{G2S})$
f = 200MHz